

STPS20L60C-Y

Automotive power Schottky rectifier

Datasheet – production data

Features

- Low forward voltage drop
- Negligible switching losses
- Low thermal resistance
- Avalanche capability specified
- AEC-Q101 qualified

Description

This dual center tap Schottky rectifier is suited for switched mode power supplies and high frequency DC to DC converters.

Packaged in D²PAK, this device is intended for use in high frequency inverters for automotive applications.

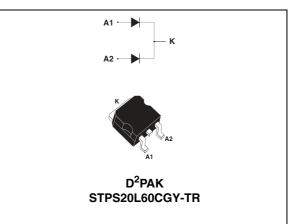


Table 1.Device summary

I _{F(AV)}	2 x 10 A
V _{RRM}	60 V
T _{j (max)}	150 °C
V _{F (max)}	0.56 V

This is information on a product in full production.

Characteristics 1

Table 2.	Absolute ratings	(limiting values.	per diode)
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Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			60	V
I _{F(RMS)}	Forward rms current			30	А
I _{F(AV)}	Average forward current $T_C = 140 \ ^{\circ}C$ Per diode $\delta = 0.5$ Per device		10 20	A	
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms, si	t _p = 10 ms, sinusoidal		А
I _{RRM}	Repetitive peak reverse current	peak reverse current $t_p = 2 \ \mu s \ square, \ F = 1 \ kHz$		1	А
P _{ARM}	Repetitive peak avalanche power $t_p = 1 \ \mu s, T_j = 25 \ ^{\circ}C$		5800	W	
T _{stg}	Storage temperature range			-65 to + 175	°C
Тj	Operating junction temperature range ⁽¹⁾			-40 to + 150	°C
dV/dt	Critical rate of rise reverse voltage			10000	V/µs

1. $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. **Thermal resistances**

Symbol	Parameter	Value	Unit
R _{th (j-c)}	Junction to case Per diode Total	1.6 0.85	°C/W
R _{th (c)}	Coupling	0.1	°C/W

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_{j(diode 1)} = P_{(diode1)} \times R_{th(j-c)}(per \ diode) + P_{(diode2)} \times R_{th(c)}$

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
L (1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}			350	μΑ
'R`´		T _j = 125 °C			65	95	mA
	V _F ⁽¹⁾ Forward voltage drop	T _j = 25 °C	I _F = 10 A			0.6	
V (1)		T _j = 125 °C	I _F = 10 A		0.48	0.56	v
VF		T _j = 25 °C	I _F = 20 A			0.74	v
		T _j = 125 °C	I _F = 20 A		0.62	0.7	

1. Pulse test: $t_p = 380 \ \mu s, \ \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.42 \text{ x } I_{F(AV)} + 0.014 \text{ x } I_{F}^{2}(RMS)$$



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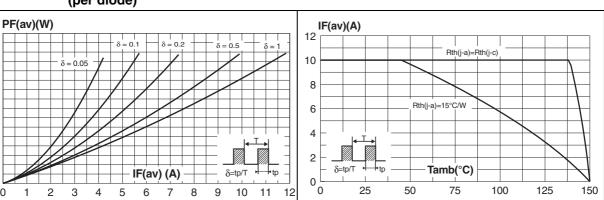
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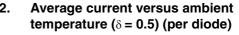
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Figure 1. Average forward power dissipation Figure 2. versus average forward current (per diode)





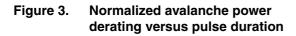
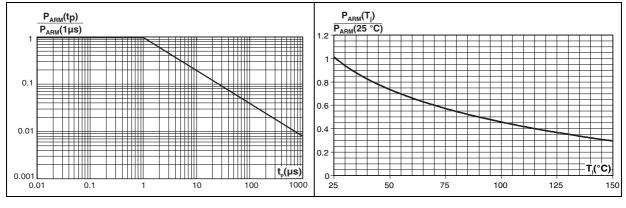
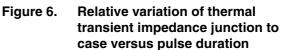


Figure 4. Normalized avalanche power derating versus junction temperature



Non repetitive surge peak forward Figure 5. current versus overload duration (maximum values, per diode)



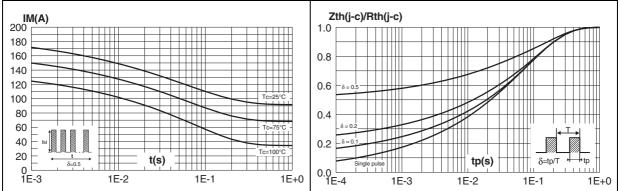
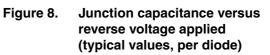




Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)



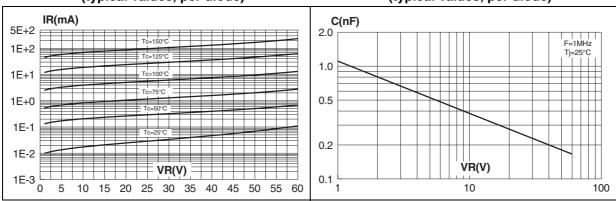
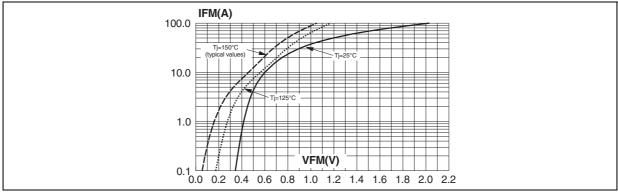


Figure 9. Forward voltage drop versus forward current (maximum values, per diode)





2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (method C)

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Table 5. D²PAK dimensions

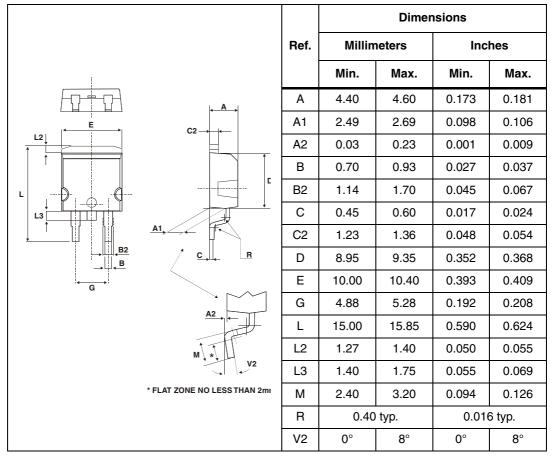
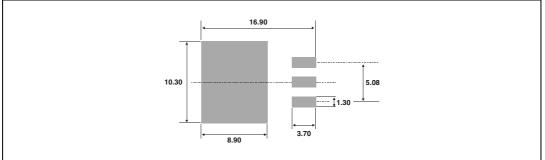


Figure 10. Footprint (dimensions in mm)





3 Ordering information

Table 6.Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS20L60CGY-TR	STPS20L60CGY	D ² PAK	1.48 g	1000	Tape and reel

4 Revision history

Table 7.Document revision history

Date	Revision	Changes
24-Oct-2012	1	Initial release.



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